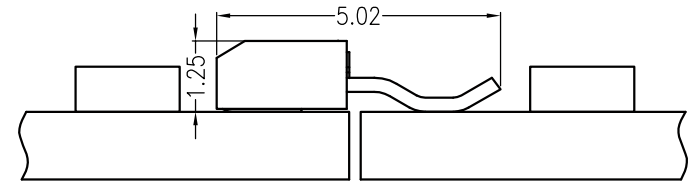


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



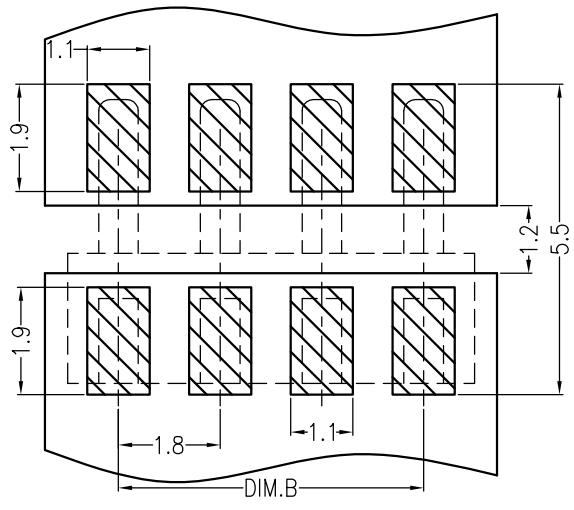
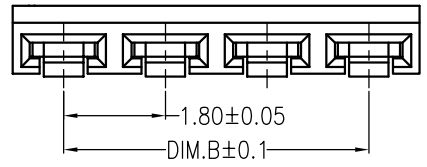
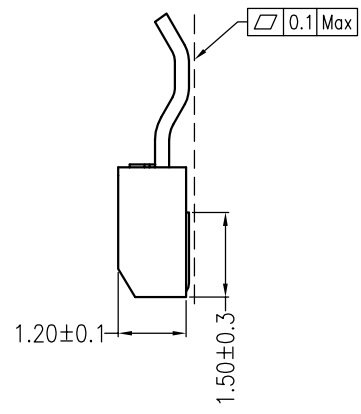
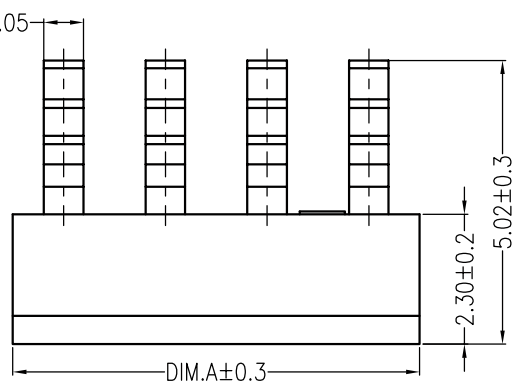
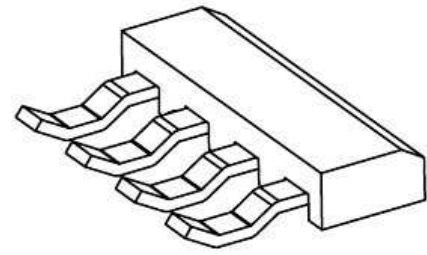
Assembly Layout

主要技术参数 Main Specifications

- 线 数 (Poles): 02 to 04
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 1000M\Omega$
- 额定电压 (Rated voltage): 125V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐 电压 (Withstand Voltage): 1000V AC/minute
- 温度范围 (Temperature Range): $-25^{\circ}C \sim +105^{\circ}C$



Circuit	Dimensions (mm)	
	DIM. A	DIM. B
02	3.60	1.80
03	5.40	3.60
04	7.20	5.40



Board Layout

C				
B	CONTACT	2~4 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
LEDsconn				TITLE: - 1.8mmPITCH 180°WAFER SMT TYPE
X.±0.5	X.±5'	USE:	PART NO.:	
.X±0.3	.X±2'	CUSTOMER		
.XX±0.25	.XX±1'	APPD:	DWG NO.:	
--	--	周秀龙		
⊕	◁	CHKD:	SCALE	
UNITS:	DR:	田峰		
mm	蒋建银		SHEET	
			1 / 1	